TelCom Semiconductor, Inc.

EVALUATION KIT AVAILABLE

TC1107

300mA CMOS LDO WITH SHUTDOWN AND V_{REF} BYPASS

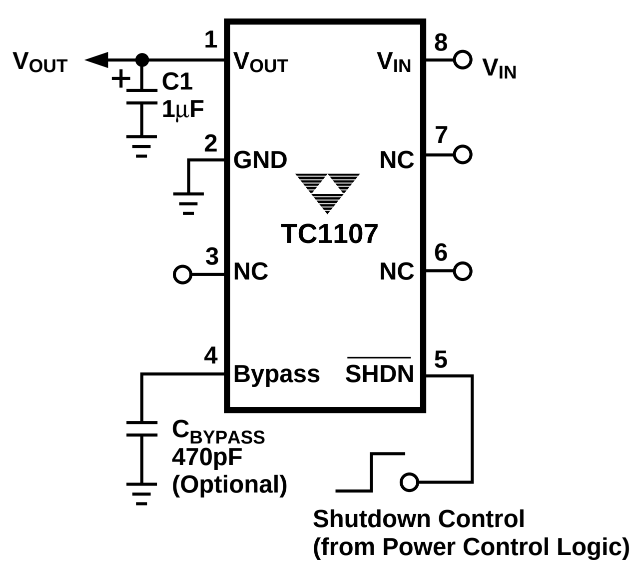
FEATURES

- Zero Ground Current for Longer Battery Life!
- Very Low Dropout Voltage
- Guaranteed 300mA Output
- High Output Voltage Accuracy
- Standard or Custom Output Voltages
- Power-Saving Shutdown Mode
- Bypass Input for Ultra-Quiet Operation
- Over-Current and Over-Temperature Protection
- Space-Saving MSOP Package Option

APPLICATIONS

- Battery-Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular / GSM / PHS Phones
- Linear Post-Regulator for SMPS
- Pagers

TYPICAL APPLICATION



GENERAL DESCRIPTION

The TC1107 is a fixed output, high accuracy (typically ±0.5%) CMOS upgrade for older (bipolar) low dropout regulators. Total supply current is typically 50µA at full load *(20 to 60 times lower than in bipolar regulators*!).

TC1107 key features include ultra low noise operation (plus optional Bypass input); very low dropout voltage (typically 240mV at full load), and fast response to step changes in load. Supply current is reduced to 0.05µA (typical) and V_{OUT} falls to zero when the shutdown input is low.

The TC1107 incorporates both over-temperature and over-current protection. The TC1107 is stable with an output capacitor of only 1µF and has a maximum output current of 300mA.

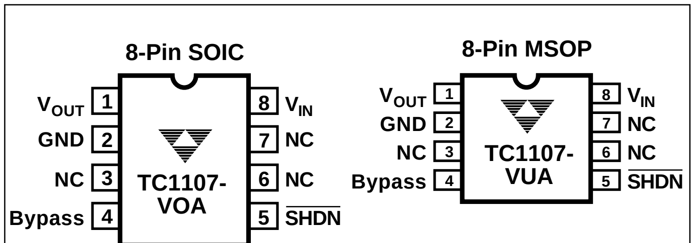
ORDERING INFORMATION

Part Number	Package	Junction Temp. Range
TC1107-xxVOA	8-Pin SOIC	– 40°C to +125°C
TC1107-xxVUA	8-Pin MSOP	– 40°C to +125°C
TC1015EV	***Evaluation Kit for CMOS LDO Family***	

Available Output Voltages:
2.5, 2.8, 3.0, 3.3, 5.0
xx indicates output voltages

Other output voltages are available. Please contact TelCom Semiconductor for details.

PIN CONFIGURATIONS



ABSOLUTE MAXIMUM RATINGS*

Input Voltage 7V
Output Voltage .... (V_{SS} – 0.3) to (V_{IN} + 0.3)
Power Dissipation .... Internally Limited (Note 6)
Operating Temperature .... – 40°C < T_J < 125°C
Storage Temperature .... – 65°C to +150°C
Maximum Voltage on Any Pin .... V_{IN} + 0.3V to – 0.3V
Lead Temperature (Soldering, 10 Sec.) .... +300°C

*Absolute Maximum Ratings indicate device operation limits beyond damage may occur. Device operation beyond the limits listed in Electrical Characteristics is not recommended.

ELECTRICAL CHARACTERISTICS:

$V_{IN} = V_{OUT} + 1V$, $I_L = 0.1\mu A$, $C_L = 3.3\mu F$, $\overline{SHDN} > V_{IH}$, $T_A = 25°C$, Unless Otherwise Noted. **Boldface** type specifications apply for junction temperatures of – 40°C to +125°C.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
V_{IN}	Input Operating Voltage		—	—	**6.5**	V
I_{OUTMAX}	Maximum Output Current		**300**	—	—	mA
V_{OUT}	Output Voltage	Note 1	— **V_R – 2.5%**	$V_R \pm 0.5\%$ —	— **V_R + 2.5%**	V
$\Delta V_{OUT}/\Delta T$	V_{OUT} Temperature Coefficient	Note 2	—	**40**	—	ppm/°C
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	$(V_R + 1V) \leq V_{IN} \leq 6V$	—	0.05	**0.35**	%
$\Delta V_{OUT}/V_{OUT}$	Load Regulation	$I_L = 0.1mA$ to I_{OUTMAX}	—	0.5	**2.0**	%
$V_{IN} - V_{OUT}$	Dropout Voltage	$I_L = 0.1mA$ $I_L = 100mA$ $I_L = 300mA$ (Note 4)	— — —	20 80 240	**30** **160** **480**	mV
I_{SS1}	Supply Current	$\overline{SHDN} = V_{IH}$	—	50	**90**	µA
I_{SS2}	Shutdown Supply Current	$\overline{SHDN} = 0V$	—	0.05	**0.5**	µA
PSRR	Power Supply Rejection Ratio	$F_{RE} \leq 1kHz$	—	60	—	dB
I_{OUTSC}	Output Short Circuit Current	$V_{OUT} = 0V$	—	550	650	mA
$\Delta V_{OUT}/\Delta P_D$	Thermal Regulation	Note 5	—	0.04	—	%/W
eN	Output Noise	F = 1Khz, $C_{OUT} = 1\mu F$, $R_{LOAD} = 50\Omega$	—	260	—	$nV/\sqrt{Hz}$
$\overline{SHDN}$ Input						
V_{IH}	$\overline{SHDN}$ Input High Threshold		**45**	—	—	$\%V_{IN}$
V_{IL}	$\overline{SHDN}$ Input Low Threshold		—	—	**15**	$\%V_{IN}$

NOTES:
1. V_R is the regulator output voltage setting.
2. $T_C V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$
3. Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
4. Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.
5. Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at V_{IN} = 6V for T = 10msec.
6. The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction-to-air (i.e. T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see *Thermal Considerations* section of this data sheet for more details.

DETAILED DESCRIPTION

The TC1107 is a precision regulator available in fixed voltages. Unlike the bipolar regulators, the TC1107 supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation at very low load currents (an important consideration in RTC and CMOS RAM battery backup applications). TC1107 pin functions are detailed below:

PIN DESCRIPTION

Pin No.	Symbol	Description
1	V_{OUT}	Regulated voltage output
2	GND	Ground terminal
3	NC	No connect
4	Bypass	Reference bypass input. Connecting a 470pF to this input further reduces output noise.
5	$\overline{SHDN}$	Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero and supply current is reduced to under 1 microamp (typical).
6	NC	No connect
7	NC	No connect
8	V_{IN}	Unregulated supply input

Figure 1 shows a typical application circuit. The regulator is enabled any time the shutdown input ($\overline{SHDN}$) is at or above V_{IH}, and shutdown (disabled) when $\overline{SHDN}$ is at or below V_{IL}. $\overline{SHDN}$ may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the $\overline{SHDN}$ input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05µA (typical), V_{OUT} falls to zero.

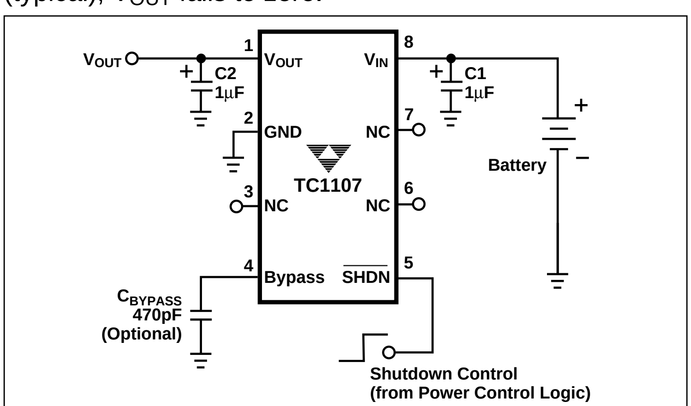


Figure 1. Typical Application Circuit

Bypass Input

A 470pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected. Larger capacitor values may be used, but results in a longer time period to rated output voltage when power is initially applied.

Output Capacitor

A 1µF (min) capacitor from V_{OUT} to ground is recommended. The output capacitor should have an effective series resistance of 5Ω or less, and a resonant frequency above 1MHz. A 1µF capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately – 30°C, solid tantalums are recommended for applications operating below – 25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

Thermal Considerations

Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case *actual* power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX}$$

Where:
P_D = worst case actual power dissipation
V_{INMAX} = maximum voltage on V_{IN}
V_{OUTMIN} = minimum regulator output voltage
$I_{LOADMAX}$ = maximum output (load) current

Equation 1.

The maximum *allowable* power dissipation (Equation 2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (125°C), and the thermal resistance from junction-to-air (θ_{JA}). The SOIC-8 package has a θ_{JA} of approximately ***160°C/Watt***, while the MSOP-8 package has a θ_{JA} of approximately ***200°C/Watt***; both when mounted on a single layer FR4 dielectric copper clad PC board.

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 2.

Equation 1 can be used in conjunction with Equation 2 to ensure regulator thermal operation is within limits. For example:

GIVEN: V_{INMAX} = 3.0V ± 10%
V_{OUTMIN} = 2.7V –2.5%
I_{LOAD} = 250mA
T_{AMAX} = 55°C
MSOP-8 Package

FIND: 1. Actual power dissipation
2. Maximum allowable dissipation.

Actual power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$
$$= [(3.0 \times 1.1) - (2.7 \times .975)]250 \times 10^{-3}$$
$$= \underline{167mW}$$

Maximum allowable power dissipation:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$
$$= \frac{(125 - 55)}{200}$$
$$= \underline{350mW}$$

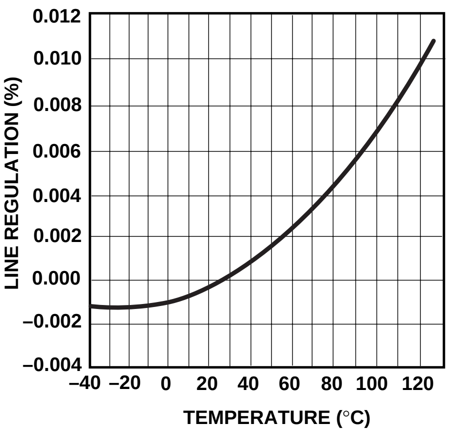
In this example, the TC1107 dissipates a maximum of only 167mW; far below the allowable limit of 350mW. In a similar manner, Equation 1 and Equation 2 can be used to calculate maximum current and/or input voltage limits.

Layout Considerations

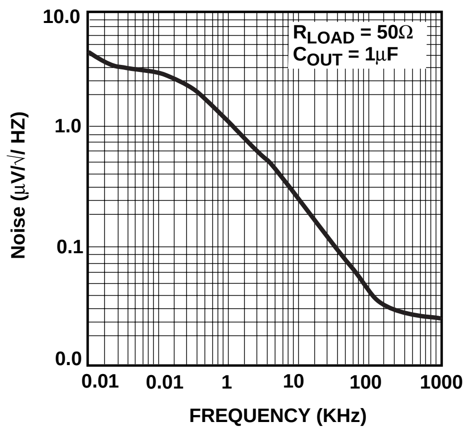
The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower θ_{JA} and, therefore, increase the maximum allowable power dissipation limit.

TYPICAL CHARACTERISTICS

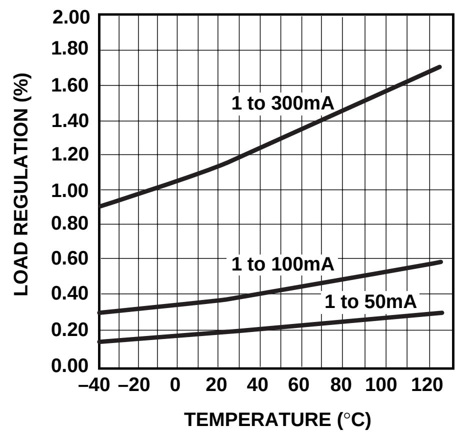
Line Regulation



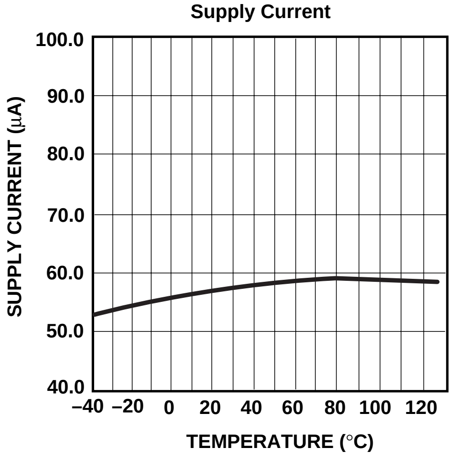
Output Noise



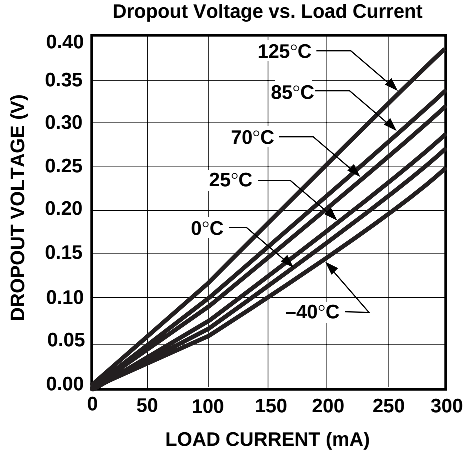
Load Regulation



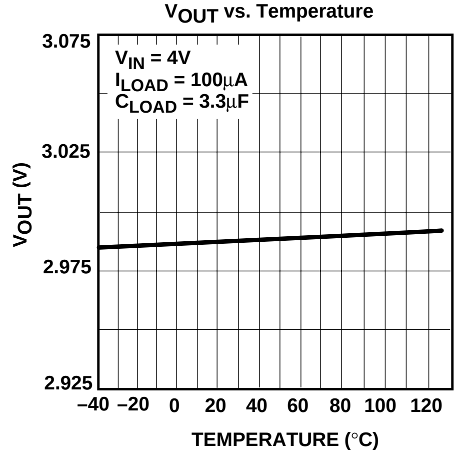
Supply Current



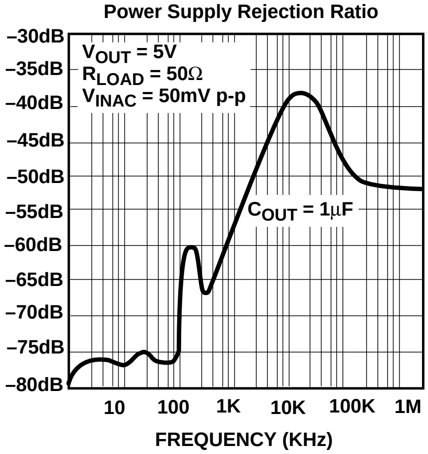
Dropout Voltage vs. Load Current



V_{OUT} vs. Temperature



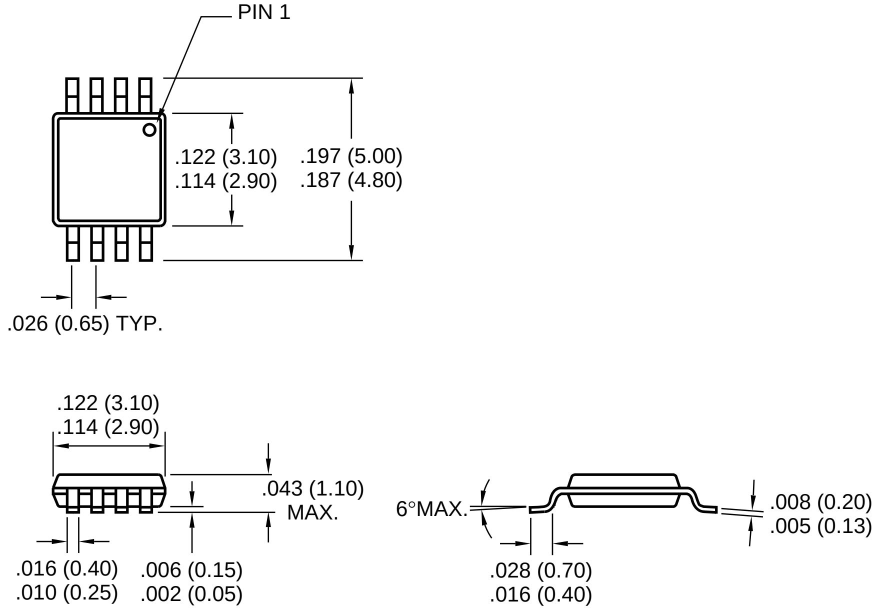
Power Supply Rejection Ratio



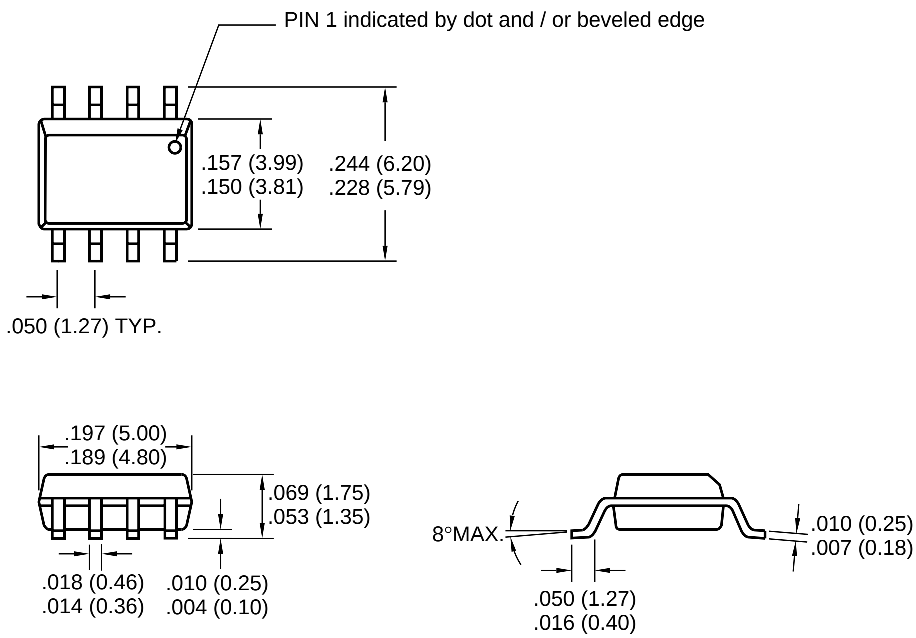
TC1107

PACKAGE DIMENSIONS

8-Pin MSOP



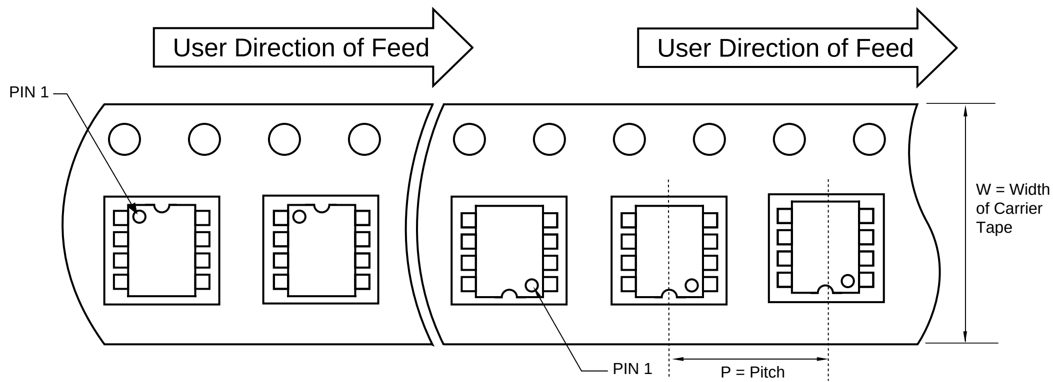
8-Pin SOIC



Dimensions: inches (mm)

TAPE AND REEL DIAGRAMS

Component Taping Orientation for MSOP Devices



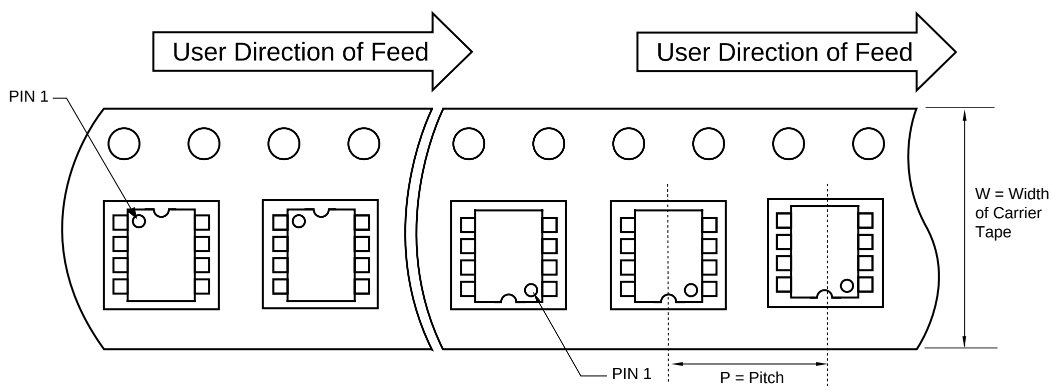
Standard Reel Component Orientation for 713 or TR Suffix Device

Reverse Reel Component Orientation for 723 or RT Suffix Device

Carrier Tape, Reel Size, and Number of Components Per Reel

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin MSOP	12 mm	8 mm	2500	13 in

Component Taping Orientation for SOIC Devices



Standard Reel Component Orientation for 713 or TR Suffix Device

Reverse Reel Component Orientation for 723 or RT Suffix Device

Carrier Tape, Reel Size, and Number of Components Per Reel

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin SOIC (N)	12 mm	8 mm	2500	13 in

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